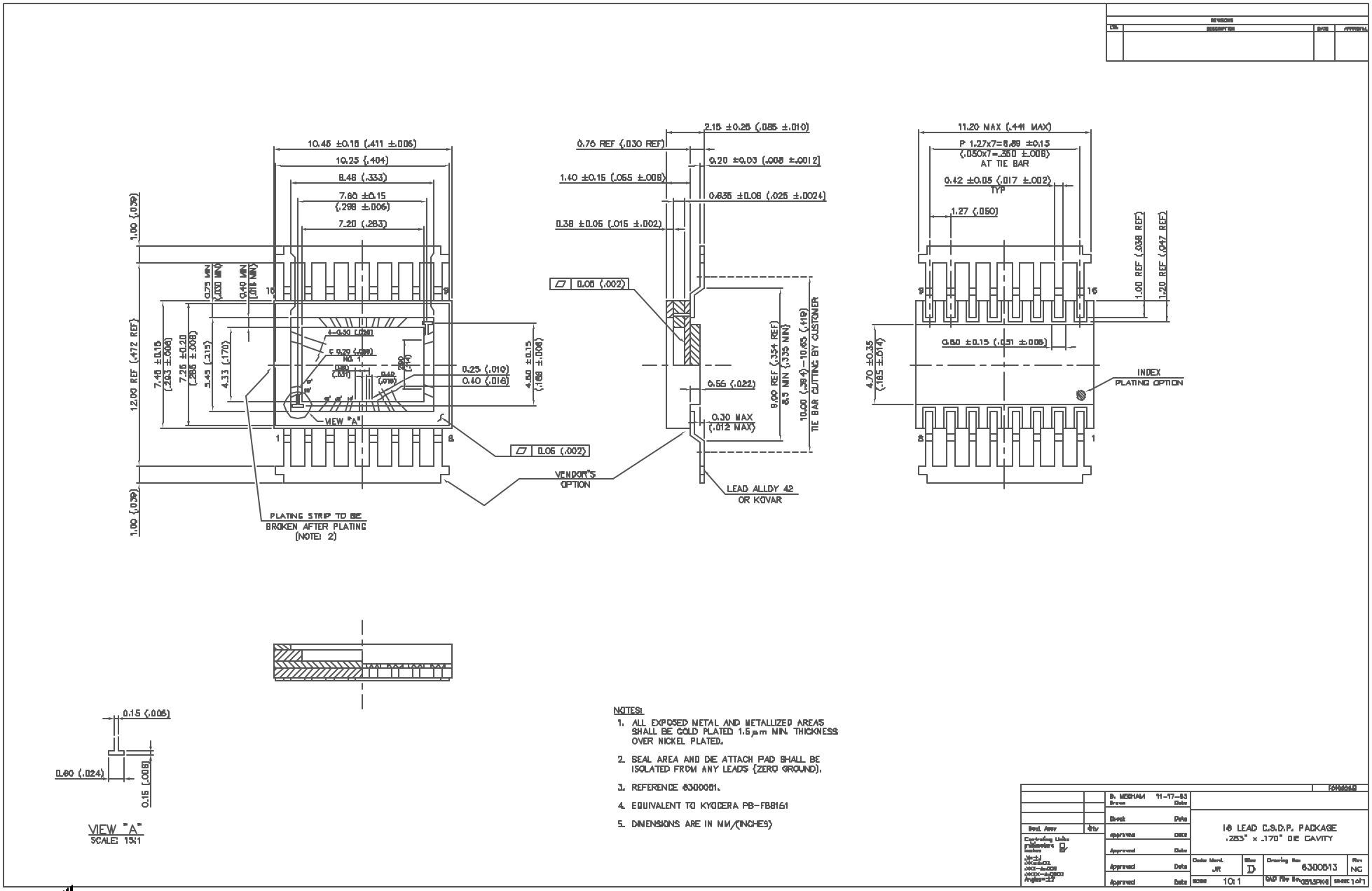
SSM P/N CSO01603



NOTES:

1. ALL EXPOSED METAL AND METALLIZED AREAS SHALL BE GOLD PLATED 1.5 μm MIN. THICKNESS OVER NICKEL PLATED.
2. SEAL AREA AND DIE ATTACH PAD SHALL BE ISOLATED FROM ANY LEADS (ZERO GROUND).
3. REFERENCE 6300051.
4. EQUIVALENT TO KYOCERA PB-FB8161
5. DIMENSIONS ARE IN MM/(INCHES)

D. MEEHAM 11-17-93 Drawn		18 LEAD C.S.D.P. PACKAGE .283" x .170" DIE CAVITY	
Check	Date		
Approved	Date		
Approved	Date		
Approved	Date		
Code Ident. JR	Size D	Drawing No. 6300513	Rev NC
SCALE 10:1		CAD File No. 0513PK6	SHEET 1 of 1

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